NE5534, NE5534A, SA5534. SA5534A LOW-NOISE OPERATIONAL AMPLIFIERS

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- Equivalent Input Noise Voltage . . . 3.5 nV/√Hz Typ
- Unity-Gain Bandwidth . . . 10 MHz Typ
- Common-Mode Rejection Ratio . . . 100 dB Typ
- High DC Voltage Gain . . . 100 V/mV Typ
- Peak-to-Peak Output Voltage Swing 32 V Typ With $V_{CC\pm}$ = ±18 V and R_L = 600 Ω
- High Slew Rate . . . 13 V/µs Typ
- Wide Supply-Voltage Range ±3 V to ±20 V
- **Low Harmonic Distortion**
- Offset Nulling Capability
- **External Compensation Capability**

NE5534, SA5534 . . . D (SOIC), P (PDIP), OR PS (SOP) PACKAGE NE5534A, SA5534A . . . D (SOIC) OR P (PDIP) PACKAGE (TOP VIEW) 8 COMP/BAL BALANCE [IN- [7 V_{CC+} 6 **∏**OUT IN+ [] 3 5 COMP

description/ordering information

The NE5534, NE5534A, SA5534, and SA5534A are high-performance operational amplifiers combining excellent dc and ac characteristics. Some of the features include very low noise, high output-drive capability, high unity-gain and maximum-output-swing bandwidths, low distortion, and high slew rate.

These operational amplifiers are compensated internally for a gain equal to or greater than three. Optimization of the frequency response for various applications can be obtained by use of an external compensation capacitor between COMP and COMP/BAL. The devices feature input-protection diodes, output short-circuit protection, and offset-voltage nulling capability with use of the BALANCE and COMP/BAL pins (see the application circuit diagram).

For the NE5534A and SA5534A, a maximum limit is specified for the equivalent input noise voltage.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



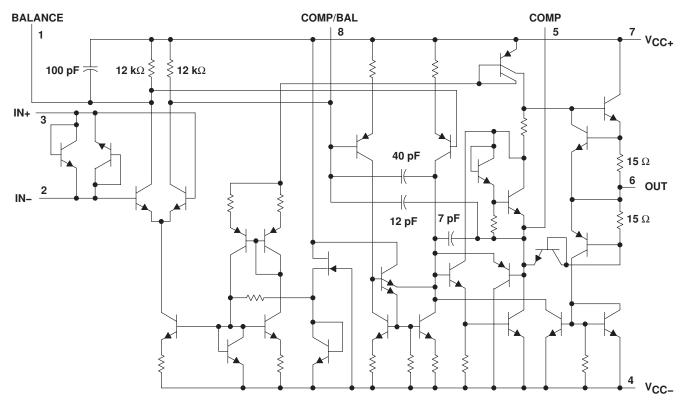
description/ordering information (continued)

ORDERING INFORMATION

TA	V _{IO} max AT 25°C	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		DDID (D)	Tube of 50	NE5534P	NE5534P	
		PDIP (P)	Tube of 50	NE5534AP	NE5534AP	
		SOIC (D)	Tube of 75	NE5534D	NECEO4	
0°C to 70°C	4 mV		Reel of 2500	NE5534DR	NE5534	
			Tube of 75	NE5534AD	55044	
			Reel of 2500	NE5534ADR	5534A	
		SOP (PS)	Reel of 2000	NE5534PSR	N5534	
	4 mV	DDID (D)	Tube of 50	SA5534P	SA5534P	
		PDIP (P)	Tube of 50	SA5534AP	SA5534AP	
		0010 (D)	Tube of 75	SA5534D	045504	
4000 1 0500			Reel of 2500	SA5534DR	SA5534	
–40°C to 85°C		SOIC (D)	Tube of 75	SA5534AD	CAFFOAA	
			Reel of 2500	SA5534ADR	SA5534A	
		000 (00)	Tube of 80	SA553APS	CAFFOA	
		SOP (PS)	Reel of 2000	SA553APSR	SA5534	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

schematic

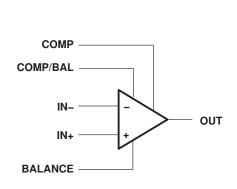


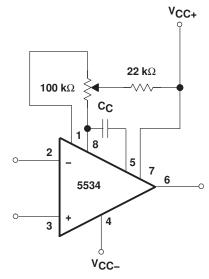
All component values shown are nominal.



symbol

application circuit





Frequency Compensation and Offset-Voltage Nulling Circuit

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage: V _{CC+} (see Note 1)	
V _{CC} – (see Note 1)	
Input voltage either input (see Notes 1 and 2)	
Input current (see Note 3)	
Duration of output short circuit (see Note 4)	Unlimited
Package thermal impedance, θ_{JA} (see Notes 5 and 6):	D package 97°C/W
	P package 85°C/W
	PS package 95°C/W
Operating virtual junction temperature, T _{.J}	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}
 - 2. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
 - 3. Excessive current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
 - 4. The output may be shorted to ground or to either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
 - 5. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	MAX	UNIT
V _{CC+}	Supply voltage		5	15	V
V _{CC} -	Supply voltage		-5	-15	V
_		NE5534, NE5534A	0	70	00
TA	Operating free-air temperature range SA5534, SA5534A				°C



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electrical characteristics, $V_{CC}^{\pm} = \pm 15 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

	PARAMETER	TEST CONDI	MIN	TYP	MAX	UNIT		
.,		$V_{O} = 0$,	T _A = 25°C		0.5	4	.,,	
V _{IO}	Input offset voltage	$R_S = 50 \Omega$	T _A = Full range			5	mV	
1	land offers and any seat	V- 0	T _A = 25°C		20	300	A	
ΙO	Input offset current	V _O = 0	T _A = Full range			400	nA	
1	Input high current	V- 0	T _A = 25°C		500	1500	~ A	
I _{IB}	Input bias current	V _O = 0	T _A = Full range			2000	nA	
V _{ICR}	Common-mode input voltage range			±12	±13		V	
V- ()		D. > 600 O	$V_{CC\pm} = \pm 15 \text{ V}$	24	26		V	
V _{O(PP)}	Maximum peak-to-peak output voltage swing	R _L ≥ 600 Ω	$V_{CC\pm} = \pm 18 \text{ V}$	30	32			
۸–	Lavas signal differential voltage amplification	$V_{O} = \pm 10 \text{ V},$	T _A = 25°C	25	100		V/mV	
AVD	Large-signal differential voltage amplification	$R_L \ge 600 \Omega$	$T_A = Full range$	15				
۸.	Cmall signal differential voltage emplification	f = 10 kHz	CC = 0		6		V/mV	
A_{vd}	Small-signal differential voltage amplification	T = TU KHZ	C _C = 22 pF		2.2		V/mv	
	Maximum-output-swing bandwidth	V _O = ±10 V	CC = 0		200		kHz	
Вом			C _C = 22 pF		95			
DOIVI	maximum capat oming canamati	$V_{CC\pm} = \pm 18 \text{ V},$ $R_L \ge 600 \Omega,$	$V_O = \pm 14 \text{ V},$ $C_C = 22 \text{ pF}$		70		- Kilz	
B ₁	Unity-gain bandwidth	$C_C = 22 pF,$	C _L = 100 pF		10		MHz	
rį	Input resistance			30	100		kΩ	
z ₀	Output impedance	$A_{VD} = 30 \text{ dB},$ $C_{C} = 22 \text{ pF},$	R _L ≥ 600 Ω, f = 10 kHz		0.3		Ω	
CMRR	Common-mode rejection ratio	$V_O = 0$, R _S = 50 Ω	VIC = VICRmin,	70	100		dB	
k _{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)	$V_{CC+} = \pm 9 \text{ V to } \pm 15 \text{ V},$ $V_{O} = 0$	$R_S = 50 \Omega$,	80	100		dB	
los	Output short-circuit current				38		mA	
ICC	Supply current	V _O = 0, No load	T _A = 25°C		4	8	mA	

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. For NE5534 and NE5534A, full range is 0°C to 70°C. For SA5534 and SA5534A, full range is –40°C to 85°C.

NE5534, NE5534A, SA5534. SA5534A LOW-NOISE OPERATIONAL AMPLIFIERS

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operating characteristics, $V_{\mbox{CC}}\,\pm$ = ± 15 V, $T_{\mbox{A}}$ = $25^{\circ}\mbox{C}$

PARAMETER		TEST CO	NDITIONS	NE5534, SA5534	' I NE5534A SA5534A			UNIT	
				TYP	MIN TYP		MAX		
CD	Classificate	C _C = 0		13		13		\//···	
SR	Slew rate	C _C = 22 pF		6		6		V/μs	
	Rise time	$V_I = 50 \text{ mV},$ A $R_I = 600 \Omega,$ C	VD = 1,	20		20		ns	
	Overshoot factor	C _L = 100 pF	OC = 22 βι	20		20		%	
t _r	Rise time	V _I = 50 mV, A	$_{\rm CC}$ = 47 pF	50		50		ns	
	Overshoot factor	$C_L = 500 \Omega$, $C_T = 500 pF$		35		35		%	
\/	Control on time to pole a voltage	f = 30 Hz		7		5.5	7	\/\(\lambda	
V _n	Equivalent input noise voltage	f = 1 kHz		4		3.5	4.5	nV/√ Hz	
		f = 30 Hz f = 1 kHz		2.5		1.5		A / (11	
In	Equivalent input noise current			0.6		0.4		pA/√Hz	
F	Average noise figure	$R_S = 5 k\Omega$, f	= 10 Hz to 20 kHz			0.9		dB	

TYPICAL CHARACTERISTICS†

NORMALIZED INPUT BIAS CURRENT AND INPUT OFFSET CURRENT vs FREE-AIR TEMPERATURE Normalized Input Bias Current and Input Offset Current 1.6 $V_{CC\pm} = \pm 15 V$ 1.4 Offset 1.2 Bias 0.8 0.6 0.4 -75 -50 -25 25 50 75 100 125 T_A - Free-Air Temperature - °C

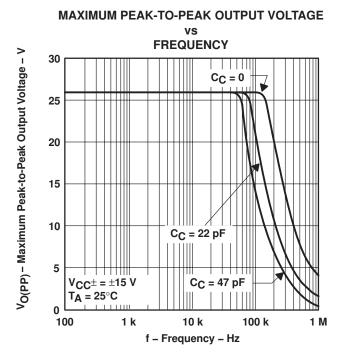
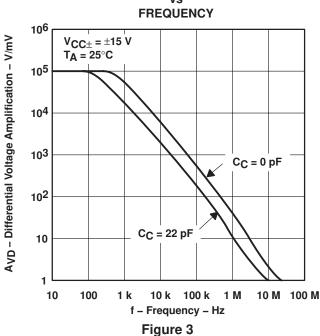


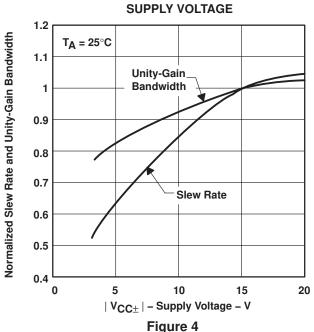
Figure 1

Figure 2





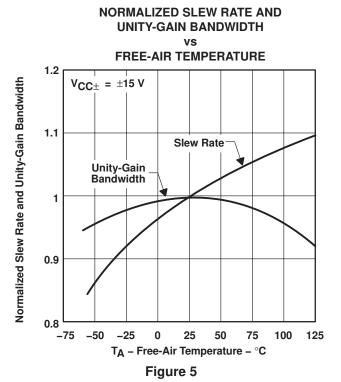
NORMALIZED SLEW RATE AND UNITY-GAIN BANDWIDTH

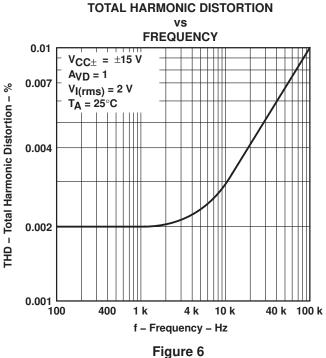


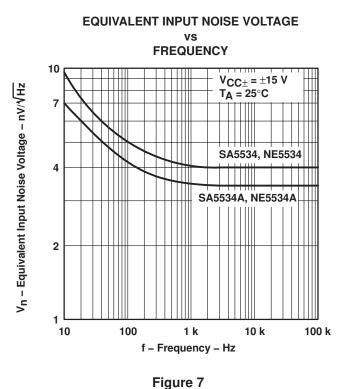
† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

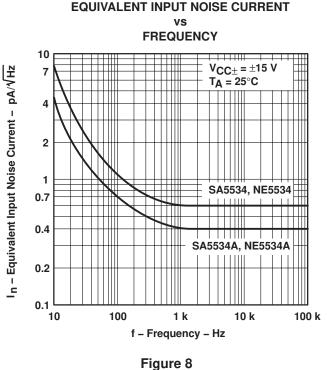


TYPICAL CHARACTERISTICS†





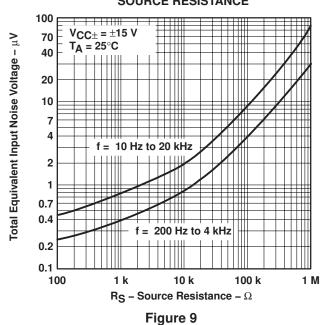




[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS

TOTAL EQUIVALENT INPUT NOISE VOLTAGE vs SOURCE RESISTANCE









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
NE5534AD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5534ADR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5534AJG	OBSOLETE	CDIP	JG	8		None	Call TI	Call TI
NE5534AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
NE5534D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5534DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
NE5534IP	OBSOLETE	PDIP	Р	8		None	Call TI	Call TI
NE5534P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
NE5534PSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SA5534AD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SA5534ADR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SA5534AP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SA5534D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SA5534DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SA5534P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SA5534PS	ACTIVE	SO	PS	8	80	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SA5534PSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

None: Not yet available Lead (Pb-Free).

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⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

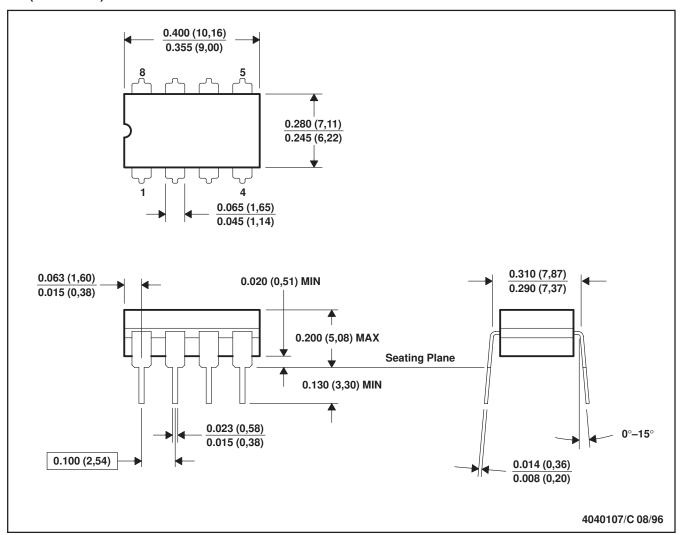
4-Mar-2005

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JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE

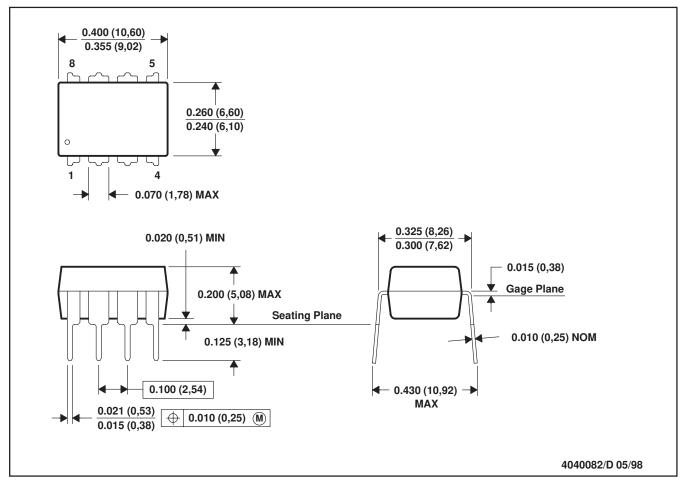


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



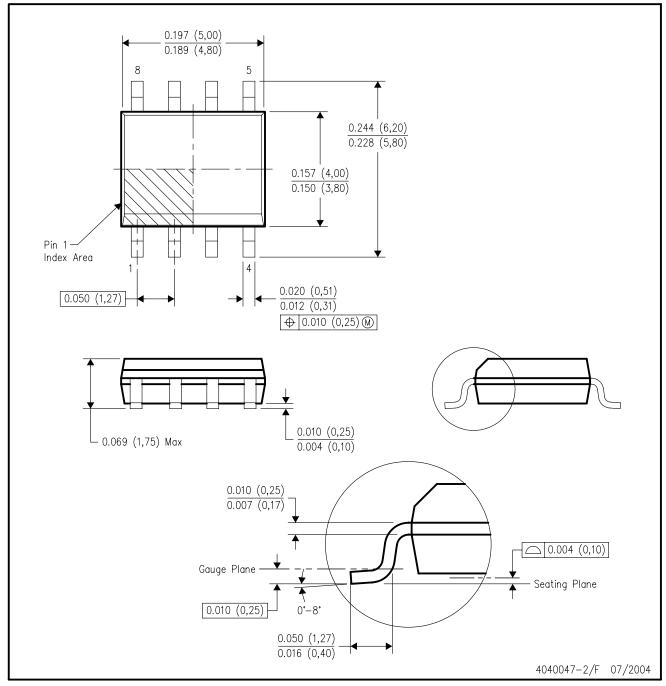
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

D (R-PDSO-G8)

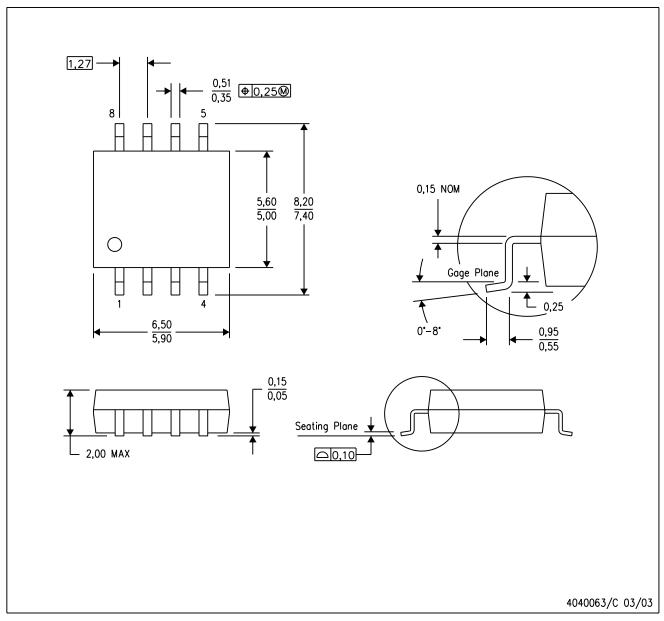
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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